

IME01-001

In the specification:

The last paragraph on P. 10 now reads as follows:

A¹

As seen in FIG. 3, arrow 33 (henceforth to be referred to as R_{Sub_Z}) represents the thermal resistance of the thermal path between balancing block 1 and the heat sink 3. Similarly, arrow 31 (R_{Chip_Z}) points to the thermal path between balancing block 1 and the chamber 6, arrow 34 (R_{Sub_X}) points to the thermal path between each pair of adjacent blocks 1 through the substrate 2, and arrow 32 (R_{Chip_X}) points to the thermal path between adjacent blocks 1 through chip 5. To obtain excellent thermal isolation between chambers 6, R_{Sub_X} and R_{Chip_X} should be much larger than R_{Sub_Z} . An approximate relation can be stated as follows:

In the claims:

✓
Please cancel claim 26.

Please amend the following claims:

- A²
1. An apparatus for simultaneously performing multiple, independently controlled, chemical reactions, comprising:
a printed circuit board mounted on a heat sink;